

**/ Descriptions**

50V ~ 1000V                      2.0A                      SMAF

Surface Mount Fast Recovery Rectifiers, Reverse Voltage 50 to1000V,Forward Current:2.0A ,SMAF thin package.

**/ Features**

RoHS                      2011/65/EU

Features: Glass Passivated Chip Junction, Fast reverse recovery time, Lead free in comply with EU ROHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

**/ Applications**

General purpose.

**/ Equivalent Circuit**

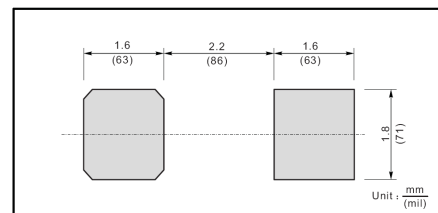


**/ Pinning**



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



**/ Marking**

See Marking Instructions.

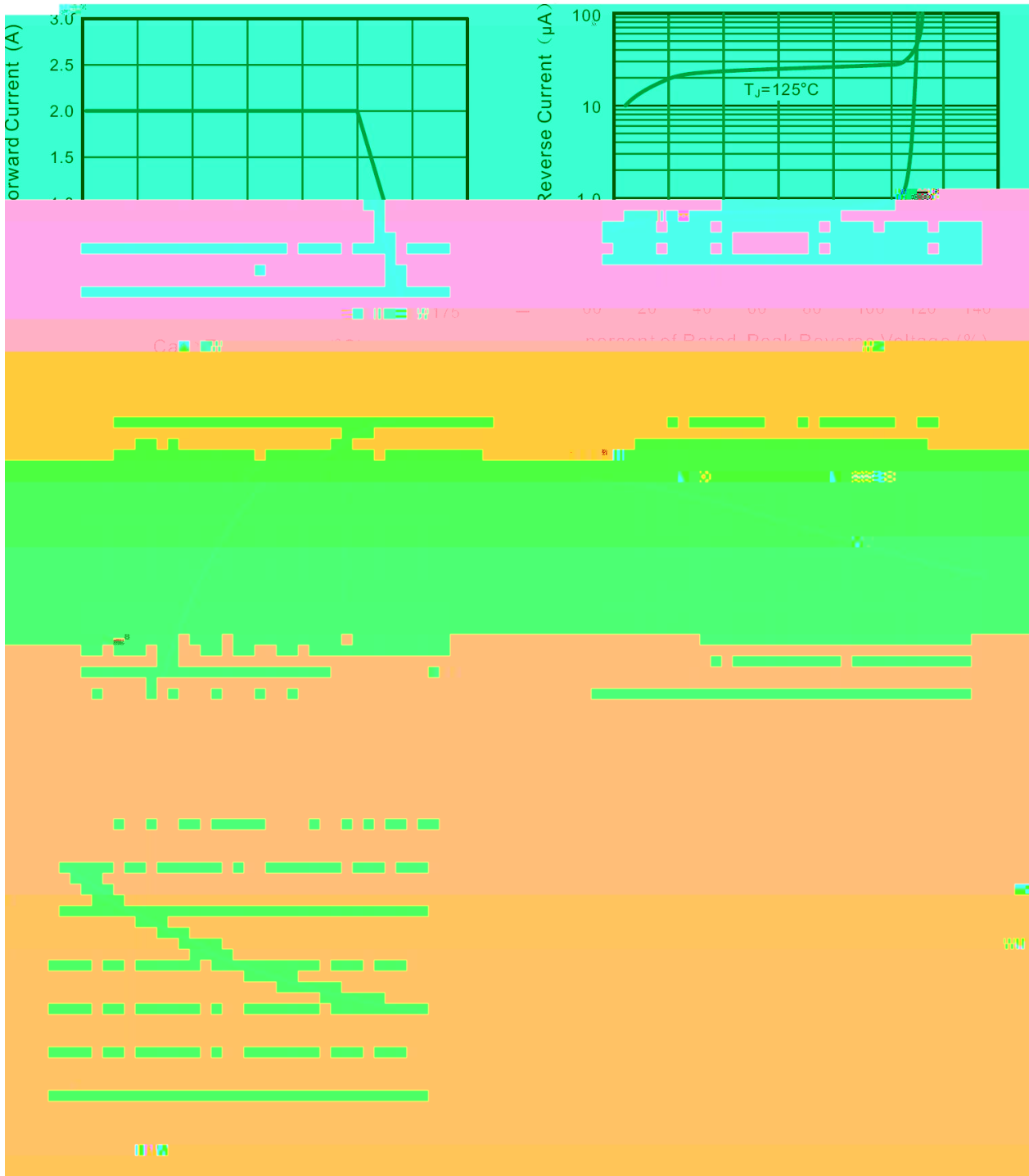
Parameter	Symbol	Rating							Unit
		RS2AF	RS2BF	RS2DF	RS2GF	RS2JF	RS2KF	RS2MF	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_a = 125^{\circ}C$	$I_{F(AV)}$	2.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	50							A
Typical Junction Capacitance <sup>1)</sup>	$C_j$	35							pF
Typical Thermal Resistance <sup>2)</sup>	$R_{\theta JA}$	60							$^{\circ}C/W$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55~+150							$^{\circ}C$

Note:

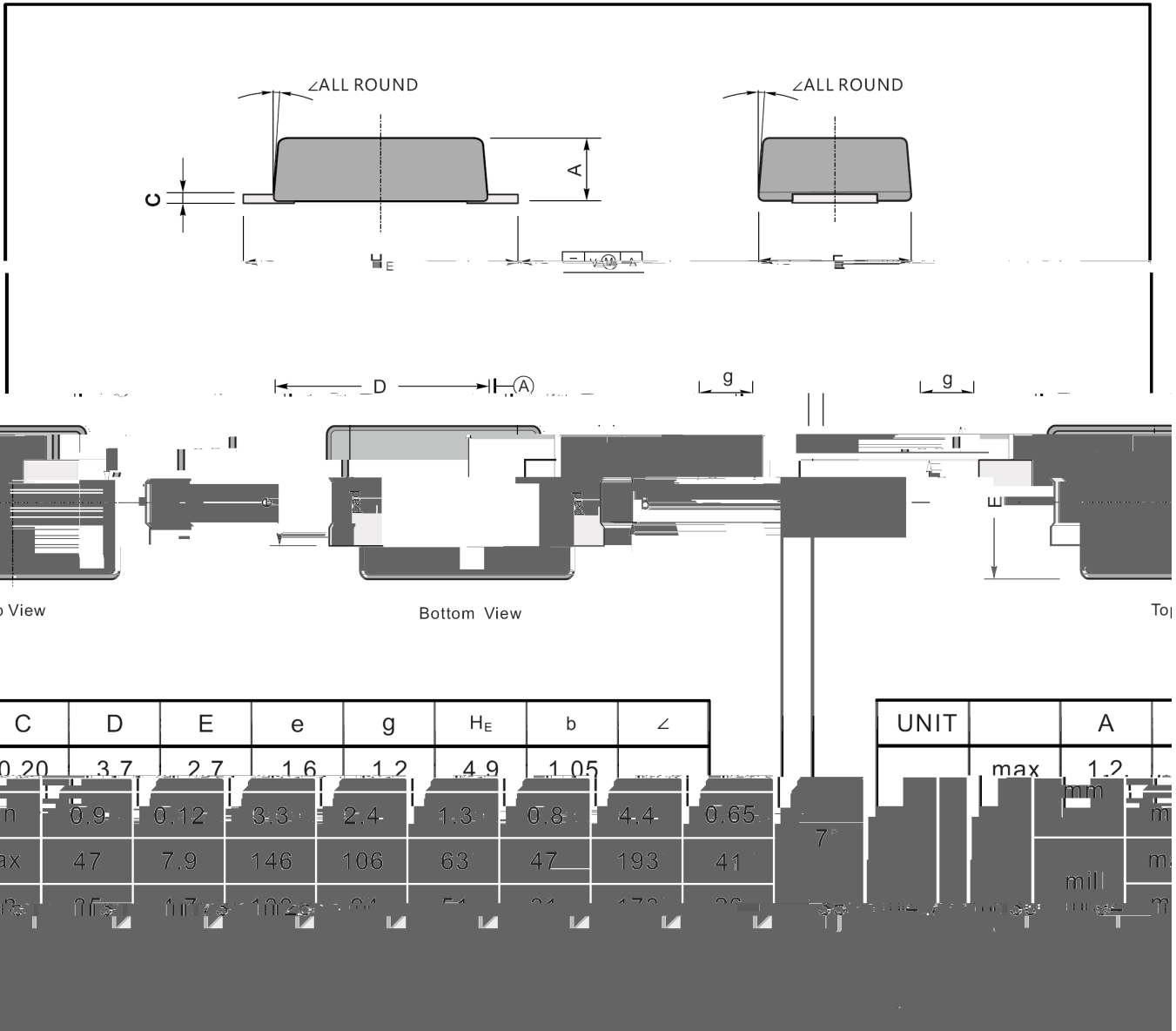
- 1 Measured at 1MHz and applied reverse voltage of 4V D.C
- 2 P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 cm) copper pad areas.

Parameter	Symbol	Test Conditions	数值 Rating							Unit
			RS2AF	RS2BF	RS2DF	RS2GF	RS2JF	RS2KF	RS2MF	

/ Electrical Characteristic Curve



/ Package Dimensions

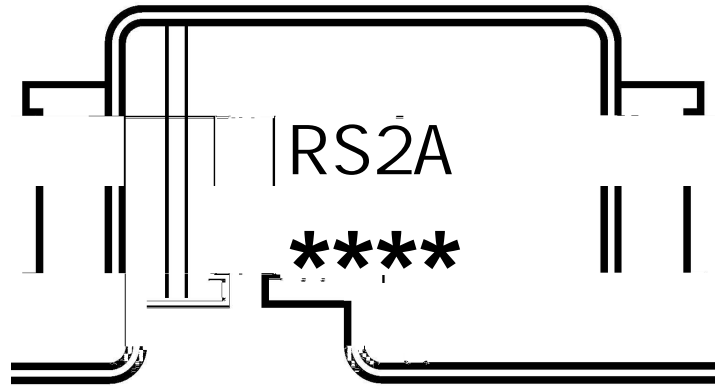


/ Marking Instructions

## Marking

Type number	Marking code
RS2AF	RS2A
RS2BF	RS2B
RS2DF	RS2D
RS2GF	RS2G
RS2JF	RS2J
RS2KF	RS2K
RS2MF	RS2M

/ Marking Instructions



RS2A  
\*\*\*\*

1 \*

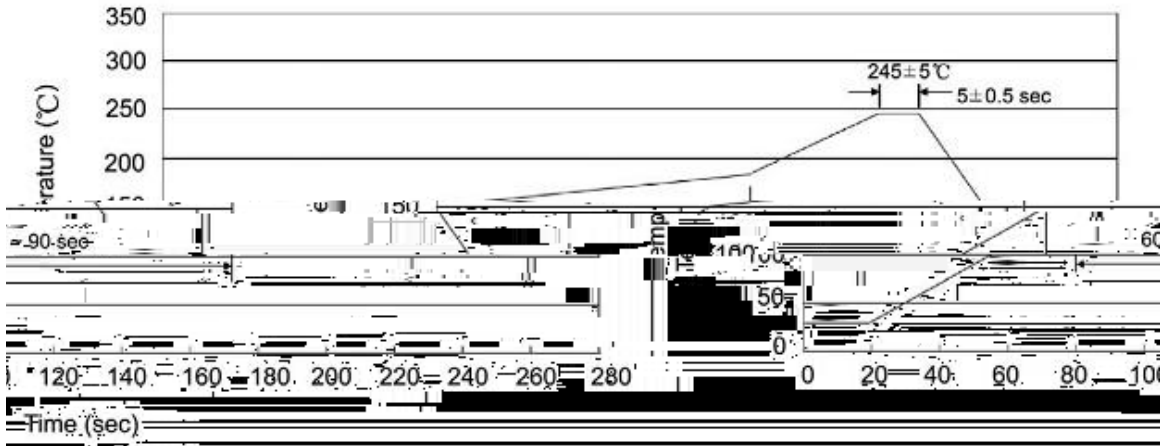
3 \*

Note:

RS2A Product Type Code

\*\*\*\* Lot No. Code The 1st \* means:YM Code The last 3 \* means:little Lot No Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |       |          |   |
|---|-------|-----|-------|----------|---|
| 1 | 150   | 180 | 60    | 90sec;   | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245±5 |     | 5±0.5 | sec;     | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       |     | 2     | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL